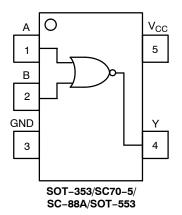
# 2-Input NOR Gate

The NL17SZ02 is a single 2-input NOR Gate in three tiny footprint packages. The device performs much as LCX multi-gate products in speed and drive.

#### **Features**

- Tiny SOT-353, SOT-553 and SOT-953 Packages
- 2.4 ns T<sub>PD</sub> at 5 V (typ)
- Source/Sink 24 mA at 3.0 V
- Over-Voltage Tolerant Inputs
- Pin For Pin with NC7SZ02P5X, TC7SZ02FU and TC7SZ02AFE
- Chip Complexity: FETs = 20
- Designed for 1.65 V to 5.5 V V<sub>CC</sub> Operation
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant



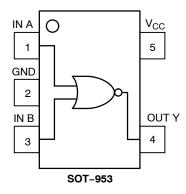


Figure 1. Pinout (Top View)

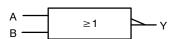


Figure 2. Logic Symbol



# ON Semiconductor®

http://onsemi.com



MARKING DIAGRAMS

SOT-353/SC70-5/SC-88A DF SUFFIX CASE 419A



L3 = Specific Device Marking

M = Date Code

= Pb-Free Package

(Note: Microdot may be in either location)



SOT-553 XV5 SUFFIX CASE 463B



L3 = Specific Device Marking
M = Date Code



SOT-953 CASE 527AE



5 = Specific Device Code

M = Month Code

# **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

# **PIN ASSIGNMENT**

(SOT-353/SC70-5/SC-88A/SOT-553)

Pin	Function	
1	Α	
2	В	
3	GND	
4	Y	
5	V <sub>CC</sub>	

# **PIN ASSIGNMENT (SOT-953)**

Pin	Function
1	IN A
2	GND
3	IN B
4	OUT Y
5	V <sub>CC</sub>

# **FUNCTION TABLE**

Inp	Output Y = A + B	
Α	В	Y
L	L	Н
L	Н	L
Н	L	L
Н	Н	L

#### **MAXIMUM RATINGS**

Symbol	Parameter	Value	Unit
V <sub>CC</sub>	DC Supply Voltage	-0.5 to +7.0	V
V <sub>IN</sub>	DC Input Voltage	-0.5 to +7.0	V
V <sub>OUT</sub>	DC Output Voltage (SOT-353/SC70-5/SC-88A/SOT-553 Packages)	-0.5 to V <sub>CC</sub> + 0.5	V
V <sub>OUT</sub>	DC Output Voltage Output at High or Low State (SOT–953 Package) Power–Down Mode (V <sub>CC</sub> = 0 V)	-0.5 to V <sub>CC</sub> + 0.5 -0.5 to + 0.5	V
I <sub>IK</sub>	DC Input Diode Current	-50	mA
l <sub>OK</sub>	DC Output Diode Current V <sub>OUT</sub> < GND, V <sub>OUT</sub> > V <sub>CC</sub> (SOT–353/SC70–5/SC–88A/SOT–553 Packages)	±50	mA
I <sub>OK</sub>	DC Output Diode Current (SOT-953 Package) V <sub>OUT</sub> < GND	-50	mA
I <sub>OUT</sub>	DC Output Sink Current	±50	mA
I <sub>CC</sub>	DC Supply Current per Supply Pin	±100	mA
T <sub>STG</sub>	Storage Temperature Range	−65 to +150	°C
TL	Lead Temperature, 1 mm from Case for 10 Seconds	260	°C
TJ	Junction Temperature Under Bias	+150	°C
$\theta_{\sf JA}$	Thermal Resistance SOT-353 (Note 1) SOT-553	350 496	°C/W
P <sub>D</sub>	Power Dissipation in Still Air at 85°C SOT–353 SOT–553	186 135	mW
MSL	Moisture Sensitivity	Level 1	
F <sub>R</sub>	Flammability Rating Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	
ESD	ESD Classification  Human Body Model (Note 2)  Machine Model (Note 3)  Charged Device Model (Note 4)	Class 2 Class A N/A	
I <sub>LATCHUP</sub>	Latchup Performance Above V <sub>CC</sub> and Below GND at 125°C (Note 5)	±100	mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2-ounce copper trace with no air flow.
   Tested to EIA/JESD22-A114-A, rated to EIA/JESD22-A114-B.
   Tested to EIA/JESD22-A115-A, rated to EIA/JESD22-A115-A.

- 4. Tested to JESD22-C101-A.
- 5. Tested to EIA/JESD78.

# **RECOMMENDED OPERATING CONDITIONS**

Symbol	Parameter	Min	Max	Unit	
V <sub>CC</sub>	DC Supply Voltage	1.65	5.5	V	
V <sub>IN</sub>	DC Input Voltage	0	5.5	V	
V <sub>OUT</sub>	DC Output Voltage (SOT-353/SC70-5/SC-88A/SOT-553 Packages)	0	5.5	V	
V <sub>OUT</sub>	DC Output Voltage (SOT-953 Package)		0	V <sub>CC</sub>	V
T <sub>A</sub>	Operating Temperature Range		-55	+125	°C
t <sub>r</sub> , t <sub>f</sub>	Input Rise and Fall Time V <sub>CC</sub> = V <sub>CC</sub> =	3.0 V ± 0.3 V 5.0 V ± 0.5 V	0 0	100 20	ns/V

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

#### DC ELECTRICAL CHARACTERISTICS

			V <sub>CC</sub>	T,	<sub>A</sub> = 25°(	2	-55°C ≤ T	A ≤ 125°C	
Symbol	Parameter	Condition	(V)	Min	Тур	Max	Min	Max	Unit
V <sub>IH</sub>	High-Level Input Voltage		1.65 to 1.95 2.3 to 5.5	0.75 V <sub>CC</sub> 0.7 V <sub>CC</sub>			0.75 V <sub>CC</sub> 0.7 V <sub>CC</sub>		٧
V <sub>IL</sub>	Low-Level Input Voltage		1.65 to 1.95 2.3 to 5.5			0.25 V <sub>CC</sub> 0.3 V <sub>CC</sub>		0.25 V <sub>CC</sub> 0.3 V <sub>CC</sub>	٧
V <sub>ОН</sub>	High-Level Output Voltage V <sub>IN</sub> = V <sub>IL</sub> or V <sub>IH</sub>	$I_{OH} = -100 \mu A$ $I_{OH} = -3 mA$ $I_{OH} = -8 mA$ $I_{OH} = -12 mA$ $I_{OH} = -16 mA$ $I_{OH} = -24 mA$ $I_{OH} = -32 mA$	1.65 to 5.5 1.65 2.3 2.7 3.0 3.0 4.5	V <sub>CC</sub> - 0.1 1.29 1.9 2.2 2.4 2.3 3.8	V <sub>CC</sub> 1.52 2.1 2.4 2.7 2.5 4.0		V <sub>CC</sub> - 0.1 1.29 1.9 2.2 2.4 2.3 3.8		V
V <sub>OL</sub>	Low-Level Output Voltage V <sub>IN</sub> = V <sub>IH</sub> or V <sub>OH</sub>	$I_{OL} = 100 \ \mu\text{A}$ $I_{OL} = 3 \ \text{mA}$ $I_{OL} = 8 \ \text{mA}$ $I_{OL} = 12 \ \text{mA}$ $I_{OL} = 16 \ \text{mA}$ $I_{OL} = 24 \ \text{mA}$ $I_{OL} = 32 \ \text{mA}$	1.65 to 5.5 1.65 2.3 2.7 3.0 3.0 4.5		0.08 0.20 0.22 0.28 0.38 0.42	0.1 0.24 0.3 0.4 0.4 0.55		0.1 0.24 0.3 0.4 0.4 0.55	V
I <sub>IN</sub>	Input Leakage Current	V <sub>IN</sub> = 5.5 V or GND	0 to 5.5			± 0.1		±1.0	μΑ
l <sub>OFF</sub>	Power Off Leakage Current (SOT-353/ SC70-5/SC-88A/ SOT-553 Packages)	V <sub>IN</sub> = 5.5 V or V <sub>OUT</sub> = 5.5 V	0			1		10	μΑ
I <sub>CC</sub>	Quiescent Supply Current	V <sub>IN</sub> = 5.5 V or GND	5.5			1		10	μΑ

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

# AC ELECTRICAL CHARACTERISTICS $t_R$ = $t_F$ = 3.0 ns

			V <sub>CC</sub>	•	Γ <sub>A</sub> = 25°C	;	-55°C ≤ T	<sub>A</sub> ≤ 125°C	
Symbol	Parameter	Condition	(V)	Min	Тур	Max	Min	Max	Unit
t <sub>PLH</sub>	Propagation Delay	$R_L = 1 \text{ M}\Omega, C_L = 15 \text{ pF}$	1.65	2.0	5.3	11.5	2.0	12.0	ns
t <sub>PHL</sub>	(Figure 3 and 4)	$R_L = 1 M\Omega, C_L = 15 pF$	1.8	2.0	4.4	9.5	2.0	10.0	
		$R_L = 1 \text{ M}\Omega, C_L = 15 \text{ pF}$	2.5 ± 0.2	0.8	2.9	6.5	0.8	7.0	
		$R_L = 1 \text{ M}\Omega, C_L = 15 \text{ pF}$	$3.3 \pm 0.3$	0.5	2.3	4.5	0.5	4.7	
		$R_L = 500 \Omega, C_L = 50 pF$		1.5	2.9	5.0	1.5	5.2	
		$R_L = 1 \text{ M}\Omega, C_L = 15 \text{ pF}$	$5.0 \pm 0.5$	0.5	1.9	3.9	0.5	4.1	
		$R_L = 500 \Omega, C_L = 50 pF$		0.8	2.4	4.3	0.8	4.5	

#### **CAPACITIVE CHARACTERISTICS**

Symbol	Parameter	Condition	Typical	Unit
C <sub>IN</sub>	Input Capacitance	$V_{CC}$ = 5.5 V, $V_I$ = 0 V or $V_{CC}$	>4	pF
C <sub>PD</sub>	Power Dissipation Capacitance	10 MHz, V <sub>CC</sub> = 3.3 V, V <sub>I</sub> = 0 V or V <sub>CC</sub>	25	pF
	(Note 6)	10 MHz, $V_{CC}$ = 5.5 V, $V_I$ = 0 V or $V_{CC}$	30	

<sup>6.</sup> C<sub>PD</sub> is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: I<sub>CC(OPR)</sub> = C<sub>PD</sub> • V<sub>CC</sub> • f<sub>in</sub> + I<sub>CC</sub>. C<sub>PD</sub> is used to determine the no–load dynamic power consumption; P<sub>D</sub> = C<sub>PD</sub> • V<sub>CC</sub><sup>2</sup> • f<sub>in</sub> + I<sub>CC</sub> • V<sub>CC</sub>.

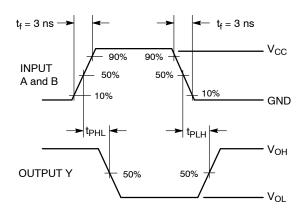
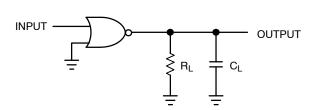


Figure 3. Switching Waveform



A 1-MHz square input wave is recommended for propagation delay tests.

Figure 4. Test Circuit

#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
NL17SZ02DFT2G	SC-88A/SOT-353/SC-70-5 (Pb-Free)	3000 / Tape & Reel
NLV17SZ02DFT2G*	SC-88A/SOT-353/SC-70-5 (Pb-Free)	3000 / Tape & Reel
NL17SZ02XV5T2G	SOT-553 (Pb-Free)	4000 / Tape & Reel
NL17SZ02P5T5G	SOT-953 (Pb-Free)	8000 / Tape & Reel

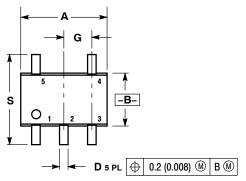
<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

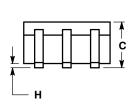
<sup>\*</sup>NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable.

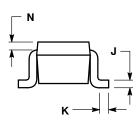
# **PACKAGE DIMENSIONS**

# SC-88A (SC-70-5/SOT-353)

CASE 419A-02 **ISSUE L** 







- NOTES:

  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

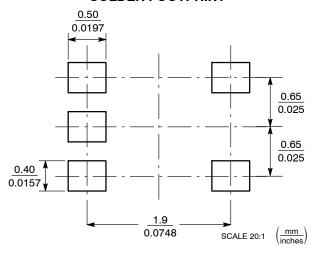
  2. CONTROLLING DIMENSION: INCH.

  3. 419A-01 OBSOLETE. NEW STANDARD 419A-02.

  4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.071	0.087	1.80	2.20
В	0.045	0.053	1.15	1.35
C	0.031	0.043	0.80	1.10
D	0.004	0.012	0.10	0.30
G	0.026	BSC	0.65 BSC	
Н		0.004		0.10
J	0.004	0.010	0.10	0.25
K	0.004 0.012		0.10	0.30
N	0.008 REF		0.20	REF
S	0.079	0.087	2.00	2.20

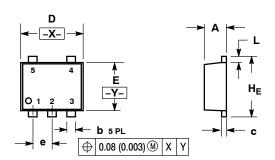
# **SOLDER FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

# **PACKAGE DIMENSIONS**

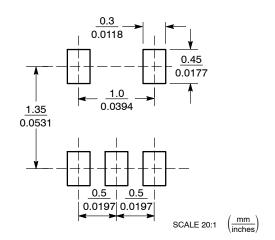
SOT-553 **XV5 SUFFIX** CASE 463B **ISSUE B** 



- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MILLIMETERS
  3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH
  THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM
  THICKNESS OF BASE MATERIAL.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.50	0.55	0.60	0.020	0.022	0.024
b	0.17	0.22	0.27	0.007	0.009	0.011
C	0.08	0.13	0.18	0.003	0.005	0.007
D	1.50	1.60	1.70	0.059	0.063	0.067
Е	1.10	1.20	1.30	0.043	0.047	0.051
е	0.50 BSC			0.020 BSC		
L	0.10	0.20	0.30	0.004	0.008	0.012
HE	1.50	1.60	1.70	0.059	0.063	0.067

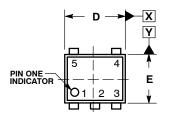
#### **SOLDERING FOOTPRINT\***



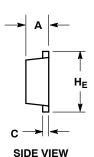
<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

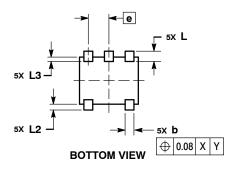
#### PACKAGE DIMENSIONS

#### SOT-953 CASE 527AE ISSUE E



**TOP VIEW** 



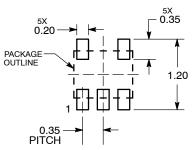


#### NOTES

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994. CONTROLLING DIMENSION: MILLIMETERS
- MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL DIMENSIONS D AND E DO NOT INCLUDE MOLD
- FLASH, PROTRUSIONS, OR GATE BURRS.

	MILLIMETERS					
DIM	MIN	NOM	MAX			
Α	0.34	0.37	0.40			
b	0.10	0.15	0.20			
С	0.07	0.12	0.17			
D	0.95	1.00	1.05			
Е	0.75	0.80	0.85			
е		0.35 BS	С			
HE	0.95	1.00	1.05			
L	(	0.175 REF				
L2	0.05	0.10	0.15			
L3			0.15			

#### **SOLDERING FOOTPRINT\***



**DIMENSIONS: MILLIMETERS** 

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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